

High Efficiency Thyristor

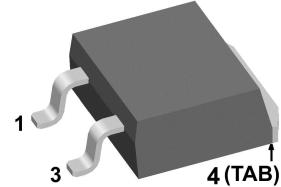
V_{RRM} = 1200 V
 I_{TAV} = 15 A
 V_T = 1.35 V

Three Quadrants operation: QI - QIII
1~ Triac

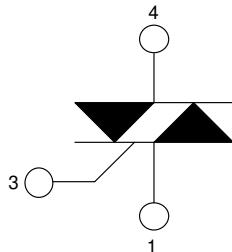
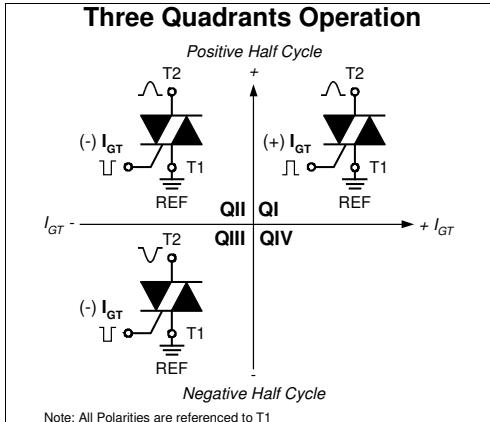
Part number

CLA30MT1200NPZ

Marking on Product: *CLA30MT1200NPZ*



Backside: anode/cathode



Features / Advantages:

- Triac for line frequency
- Three Quadrants Operation - QI - QIII
- Planar passivated chip
- Long-term stability of blocking currents and voltages

Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

Package: TO-263 (D2Pak-HV)

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- High creepage distance between terminals

Disclaimer Notice

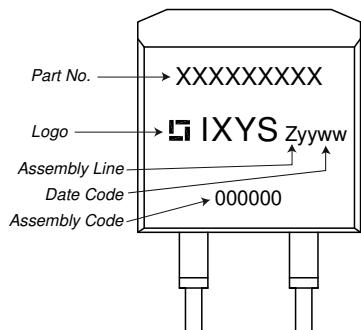
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Rectifier

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
$V_{RSM/DSM}$	max. non-repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ C$			1300	V
$V_{RRM/DRM}$	max. repetitive reverse/forward blocking voltage	$T_{VJ} = 25^\circ C$			1200	V
$I_{R/D}$	reverse current, drain current	$V_{R/D} = 1200 V$ $V_{R/D} = 1200 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		10 1.5	μA mA
V_T	forward voltage drop	$I_T = 15 A$	$T_{VJ} = 25^\circ C$		1.35	V
		$I_T = 30 A$			1.68	V
		$I_T = 15 A$	$T_{VJ} = 125^\circ C$		1.35 1.79	V V
I_{TAV}	average forward current	$T_C = 120^\circ C$	$T_{VJ} = 150^\circ C$		15	A
		180° sine			33	A
		r_T slope resistance } for power loss calculation only	$T_{VJ} = 150^\circ C$		0.89 30	V $m\Omega$
R_{thJC}	thermal resistance junction to case				0.95	K/W
R_{thCH}	thermal resistance case to heatsink			0.25		K/W
P_{tot}	total power dissipation		$T_C = 25^\circ C$		130	W
I_{TSM}	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$		170	A
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 V$		185	A
		$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 150^\circ C$		145	A
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 V$		155	A
I^2t	value for fusing	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$		145	A^2s
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 V$		140	A^2s
		$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$	$T_{VJ} = 150^\circ C$		105	A^2s
		$t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$V_R = 0 V$		100	A^2s
C_J	junction capacitance	$V_R = 400 V$ $f = 1 \text{ MHz}$	$T_{VJ} = 25^\circ C$	9		pF
P_{GM}	max. gate power dissipation	$t_p = 30 \mu s$	$T_C = 150^\circ C$		5	W
		$t_p = 300 \mu s$			1	W
P_{GAV}	average gate power dissipation				0.2	W
$(di/dt)_{cr}$	critical rate of rise of current	$T_{VJ} = 150^\circ C; f = 50 \text{ Hz}$ repetitive, $I_T = 45 A$			150	$A/\mu s$
		$t_p = 200 \mu s; di_G/dt = 0.3 A/\mu s;$				
		$I_G = 0.3 A; V = \frac{2}{3} V_{DRM}$ non-repet., $I_T = 15 A$			500	$A/\mu s$
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150^\circ C$		500	$V/\mu s$
		$R_{GK} = \infty$; method 1 (linear voltage rise)				
V_{GT}	gate trigger voltage	$V_D = 6 V$	$T_{VJ} = 25^\circ C$		1.3	V
			$T_{VJ} = -40^\circ C$		1.6	V
I_{GT}	gate trigger current	$V_D = 6 V$	$T_{VJ} = 25^\circ C$		± 40	mA
			$T_{VJ} = -40^\circ C$		± 60	mA
V_{GD}	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150^\circ C$		0.2	V
I_{GD}	gate non-trigger current				± 1	mA
I_L	latching current	$t_p = 10 \mu s$	$T_{VJ} = 25^\circ C$		70	mA
		$I_G = 0.3 A; di_G/dt = 0.3 A/\mu s$				
I_H	holding current	$V_D = 6 V$ $R_{GK} = \infty$	$T_{VJ} = 25^\circ C$		50	mA
t_{gd}	gate controlled delay time	$V_D = \frac{1}{2} V_{DRM}$	$T_{VJ} = 25^\circ C$		2	μs
		$I_G = 0.3 A; di_G/dt = 0.3 A/\mu s$				
t_q	turn-off time	$V_R = 100 V; I_T = 15 A; V = \frac{2}{3} V_{DRM}$ $T_{VJ} = 125^\circ C$	$di/dt = 10 A/\mu s$ $dv/dt = 20 V/\mu s$ $t_p = 200 \mu s$	150		μs

Package TO-263 (D2Pak-HV)

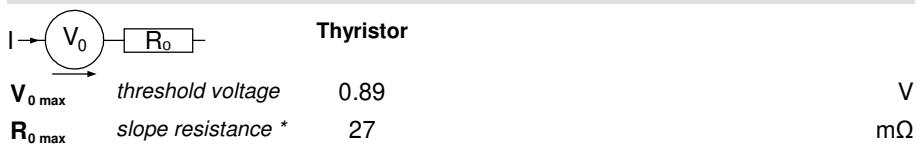
Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
I_{RMS}	RMS current	per terminal			35	A
T_{VJ}	virtual junction temperature		-40		150	°C
T_{op}	operation temperature		-40		125	°C
T_{stg}	storage temperature		-40		150	°C
Weight				1.5		g
F_c	mounting force with clip		20		60	N
$d_{Spp/App}$	creepage distance on surface / striking distance through air	terminal to terminal	4.2			mm
$d_{Spb/Apb}$		terminal to backside	4.7			mm

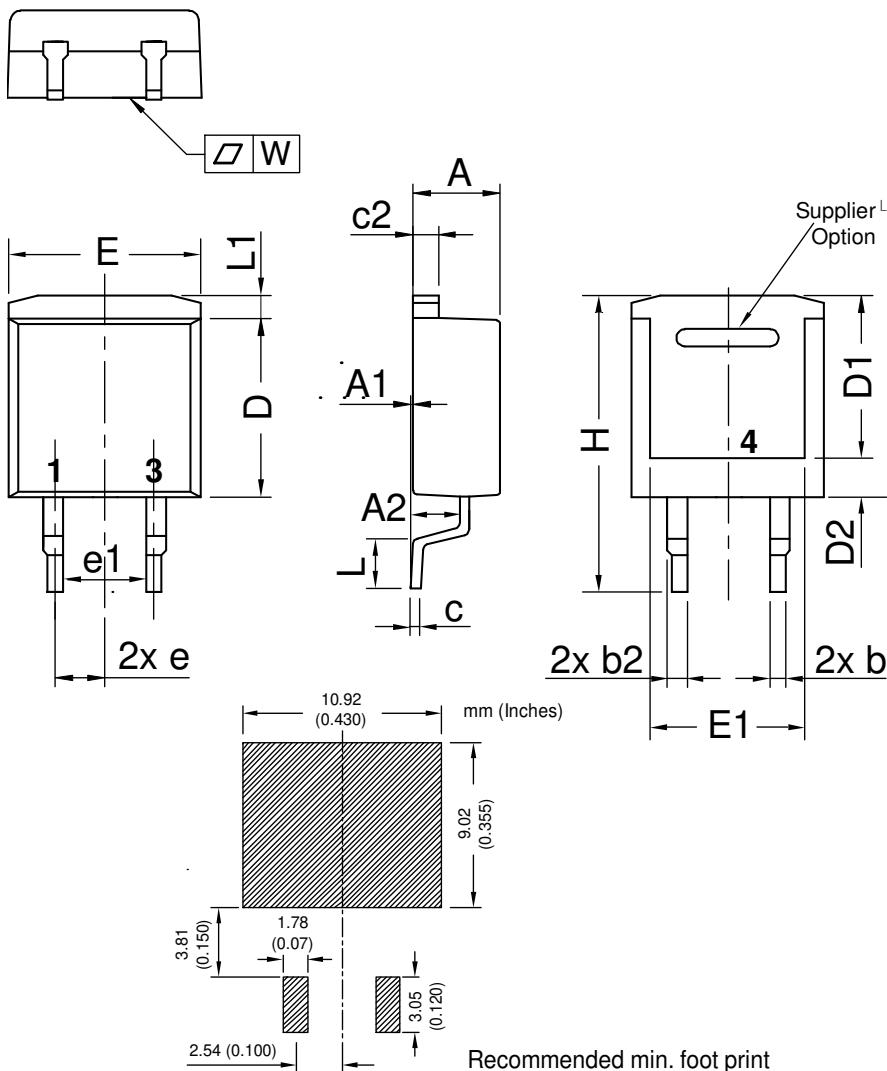
Product Marking

Part description

C = Thyristor (SCR)
 L = High Efficiency Thyristor
 A = (up to 1200V)
 30 = Current Rating [A]
 MT = 1~ Triac
 1200 = Reverse Voltage [V]
 N = Three Quadrants operation: QI - QIII
 PZ = TO-263AB (D2Pak) (2HV)

Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	CLA30MT1200NPZ-TRL	CLA30MT1200NPZ	Tape & Reel	800	516960
Alternative	CLA30MT1200NPZ-TUB	CLA30MT1200NPZ	Tube	50	525255

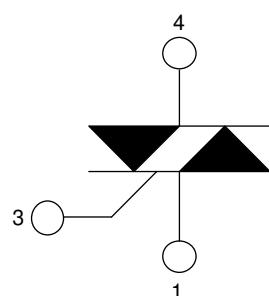
Similar Part	Package	Voltage class
CLA30MT1200NPB	TO-220AB (3)	1200

Equivalent Circuits for Simulation
** on die level*
 $T_{VJ} = 150 \text{ }^{\circ}\text{C}$


Outlines TO-263 (D2Pak-HV)


Dim.	Millimeter		Inches	
	min	max	min	max
A	4.06	4.83	0.160	0.190
A1	typ. 0.10		typ. 0.004	
A2	2.41		0.095	
b	0.51	0.99	0.020	0.039
b2	1.14	1.40	0.045	0.055
c	0.40	0.74	0.016	0.029
c2	1.14	1.40	0.045	0.055
D	8.38	9.40	0.330	0.370
D1	8.00	8.89	0.315	0.350
D2	2.3		0.091	
E	9.65	10.41	0.380	0.410
E1	6.22	8.50	0.245	0.335
e	2,54 BSC		0,100 BSC	
e1	4.28		0.169	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	1.02	1.68	0.040	0.066
W	typ. 0.02		typ. 0.0008	0.002

All dimensions conform with
and/or within JEDEC standard.



Thyristor

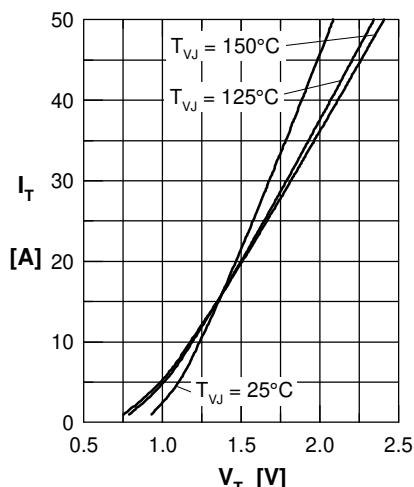


Fig. 1 Forward characteristics

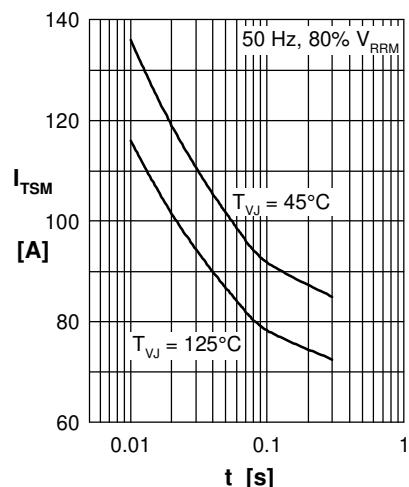


Fig. 2 Surge overload current

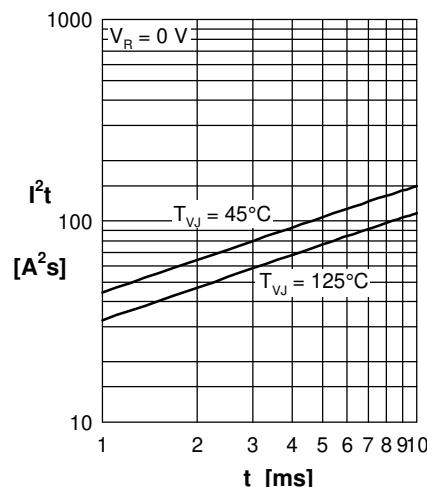


Fig. 3 I^2t versus time (1-10 ms)

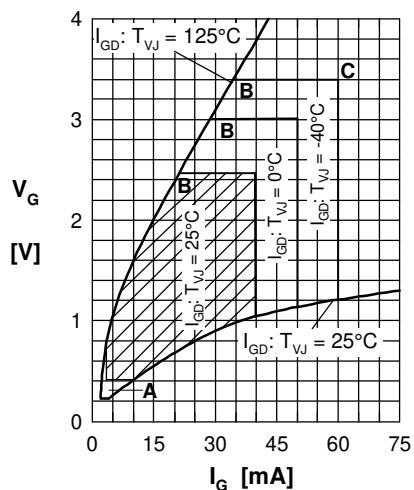


Fig. 4 Gate trigger characteristics

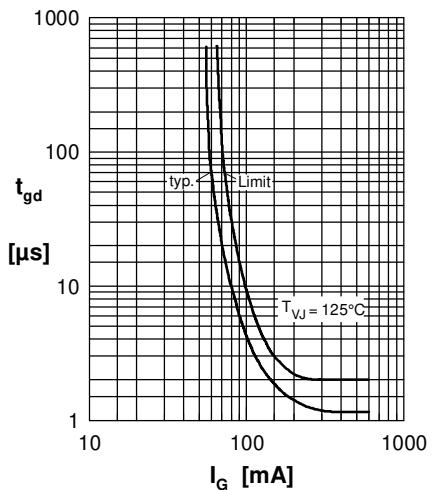


Fig. 5 Gate controlled delay time

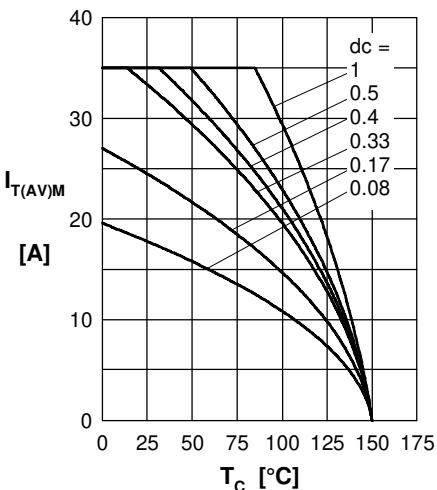


Fig. 6 Max. forward current at case temperature

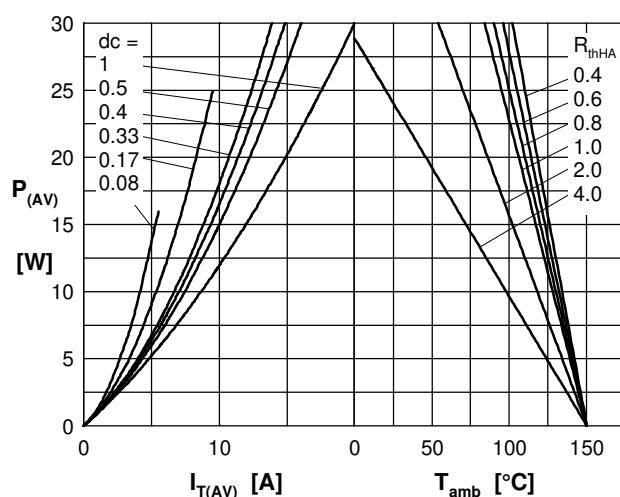


Fig. 7a Power dissipation versus direct output current
Fig. 7b and ambient temperature

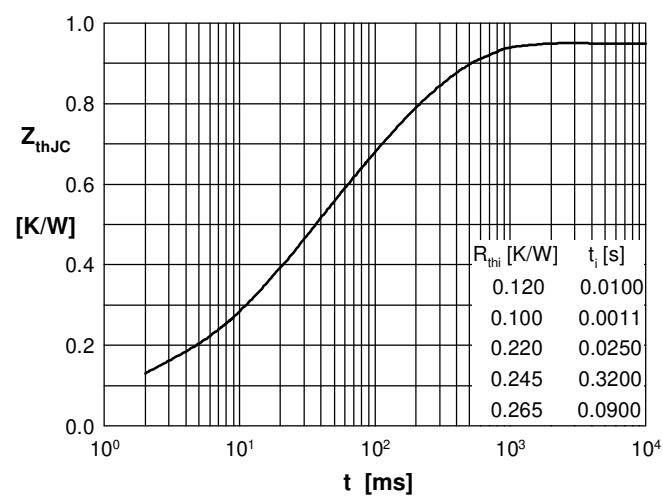


Fig. 8 Transient thermal impedance